

**REMARKS**

Applicants elect Group I, i.e., claims 11-21. Applicants are amending claim 20 to replace "at least one the legs" with "at least one of the legs" and submit that this is a cosmetic amendment, which does not change the breadth of claim 20. Applicants are also adding new claims 22-31 and request consideration of all now pending claims 11-31.

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Respectfully submitted,



Robert D. Wasson  
Attorney for Applicants  
Reg. No. 40,218

LAW OFFICES OF  
SEJVERN MORRILL LLP  
3 EMBARCADERO CENTER  
28<sup>TH</sup> FLOOR  
SAN FRANCISCO, CA 94111  
(415) 217-6000  
FAX (415) 434-0646

## ATTACHMENT A

### Version of claims with markings to show changes made

The addition to claim 20 is shown in bold and underlined.

Claim 20 has been amended as follows:

20. (Amended) The semiconductor chip package of claim 12 wherein at least one of the legs of the shield element comprises a convex lower surface, and wherein a corresponding one of the bond fingers comprises a concave upper surface shaped to receive the convex lower surface of the leg.

LAW OFFICES OF  
SILVERMAN MORRILL LLP  
3 EMBARCADERO CENTER  
28<sup>TH</sup> FLOOR  
SAN FRANCISCO, CA 94111  
(415) 217-6000  
FAX (415) 434-0646